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(54) Title: SEMICONDUCTOR WAFER PROCESSING ADHESIVES AND TAPES

(57) Abstract

A semiconductor wafer processing tape comprises a permanent backing and a layer of a non-pressure sensitive adhesive comprising a thermoplastic elastomer block copolymer on the permanent backing. Optionally, the adhesive may include an adhesion modifier such as a tackifying resin, a liquid rubber or a photocrosslinking agent. The tapes are useful for both wafer grinding and wafer dicing applications. A method of processing semiconductor wafers is disclosed.

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